# Octal 3-State Noninverting Bus Transceiver with LSTTL Compatible Inputs

# **High-Performance Silicon-Gate CMOS**

The MC74HCT245A is identical in pinout to the LS245. This device may be used as a level converter for interfacing TTL or NMOS outputs to High Speed CMOS inputs.

The MC74HCT245A is a 3-state noninverting transceiver that is used for 2-way asynchronous communication between data buses. The device has an active-low Output Enable pin, which is used to place the I/O ports into high-impedance states. The Direction control determines whether data flows from A to B or from B to A.

#### **Features**

- Output Drive Capability: 15 LSTTL Loads
- TTL/NMOS Compatible Input Levels
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 4.5 V to 5.5 V
- Low Input Current: 1.0 μA
- In Compliance with the Requirements Defined by JEDEC Standard No. 7 A
- Chip Complexity: 304 FETs or 76 Equivalent Gates
- These Devices are Pb-Free and are RoHS Compliant

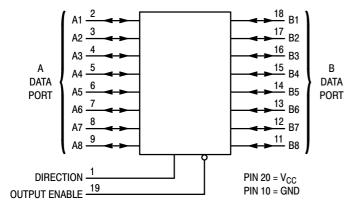


Figure 1. Logic Diagram

Design Criteria	Value	Units
Internal Gate Count*	76	ea
Internal Gate Propagation Delay	1.0	ns
Internal Gate Power Dissipation	5.0	μW
Speed Power Product	0.005	рJ

<sup>\*</sup>Equivalent to a two-input NAND gate.

#### **FUNCTION TABLE**

Control Inputs		
Output Enable Direction		Operation
L	L	Data Transmitted from Bus B to Bus A
L	Н	Data Transmitted from Bus A to Bus B
Н	Х	Buses Isolated (High-Impedance State)

1



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PDIP-20 N SUFFIX CASE 738



SOIC-20W DW SUFFIX CASE 751D

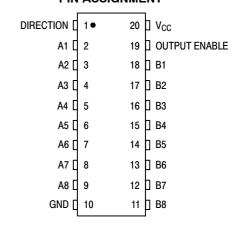


TSSOP-20 DT SUFFIX CASE 948E



SOEIAJ-20 F SUFFIX CASE 967

#### **PIN ASSIGNMENT**



#### **ORDERING INFORMATION**

See detailed ordering, shipping information, and marking information in the package dimensions section on page 6 of this data sheet.

X = Don't Care

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
V <sub>in</sub>	DC Input Voltage (Referenced to GND)	$-0.5$ to $V_{CC}$ + 0.5	V
V <sub>out</sub>	DC Output Voltage (Referenced to GND)	$-0.5$ to $V_{CC}$ + 0.5	V
l <sub>in</sub>	DC Input Current, per Pin	± 20	mA
l <sub>out</sub>	DC Output Current, per Pin	± 35	mA
Icc	DC Supply Current, V <sub>CC</sub> and GND Pins	± 75	mA
P <sub>D</sub>	Power Dissipation in Still Air, PDIP† SOIC Package† TSSOP Package†	750 500 450	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Secs (PDIP, SOIC, SSOP or TSSOP Package)	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $\mbox{GND} \leq (\mbox{V}_{in} \mbox{ or } \mbox{V}_{out}) \leq \mbox{V}_{CC}.$ 

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating — Plastic DIP: – 10 mW/°C from 65° to 125°C SOIC Package: – 7 mW/°C from 65° to 125°C

TSSOP Package: – 7 HW/ C from 65° to 125°C

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types	<b>– 55</b>	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Figure 1)	0	500	ns

#### DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Gu	arantee	d Limit	
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	– 55 to 25°C	≤ <b>85</b> °	C ≤ 125°C	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out}  \le 20 \mu\text{A}$	4.5 5.5	2.0 2.0	2.0 2.0	2.0 2.0	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out}  \le 20  \mu\text{A}$	4.5 5.5	0.8 0.8	0.8 0.8	0.8 0.8	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20 \ \mu A$	4.5 5.5	4.4 5.4	4.4 5.4	4.4 5.4	V
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 6.0 \text{ mA}$	4.5	3.98	3.84	3.7	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20 \ \mu A$	4.5 5.5	0.1 0.1	0.1 0.1	0.1 0.1	V
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 6.0 \text{ mA}$	4.5	0.26	0.33	0.4	
l <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND, Pins 1 or 19	5.5	± 0.1	± 1.0	± 1.0	μΑ
Icc	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0 \mu A$	5.5	4.0	40	160	μΑ
l <sub>OZ</sub>	Maximum Three-State Leakage Current	Output in High-Impedance State $V_{in} = V_{IL}$ or $V_{IH}$ $V_{out} = V_{CC}$ or GND, I/O Pins	5.5	± 0.5	± 5.0	± 10	μΑ
$\Delta I_{CC}$	Additional Quiescent Supply Current	V <sub>in</sub> = 2.4 V, Any One Input		≥ -55°(	2	5°C to 125°C	
	Current	$V_{in} = V_{CC}$ or GND, Other Inputs $I_{out} = 0 \mu A$	5.5	2.9		2.4	mA

# AC ELECTRICAL CHARACTERISTICS (V<sub>CC</sub> = 5.0 V $\pm$ 10%, C<sub>L</sub> = 50 pF, Input $t_{r}$ = $t_{f}$ = 6.0 ns)

	Guaranteed Limit		mit		
Symbol	Parameter	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, A to B or B to A (Figures 2 and 4)	22	28	33	ns
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Maximum Propagation Delay, Direction or Output Enable to A or B (Figures 3 and 5)	30	36	42	ns
t <sub>PZL</sub> , t <sub>PZH</sub>	Maximum Propagation Delay, Output Enable to A or 8 (Figures 3 and 5)	30	36	42	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time. any Output (Figures 2 and 4)	12	15	18	ns
C <sub>in</sub>	Maximum Input Capacitance (Pin 1 or 19)	10	10	10	pF
C <sub>out</sub>	Maximum Three-State I/O Capacitance, (I/O in High-Impedance State)	15	15	15	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
$C_{PD}$	Power Dissipation Capacitance (Per Enabled Output)*	97	рF

<sup>\*</sup>Used to determine the no–load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

#### **SWITCHING WAVEFORMS**

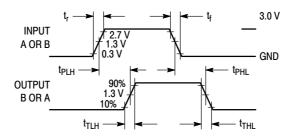


Figure 2.

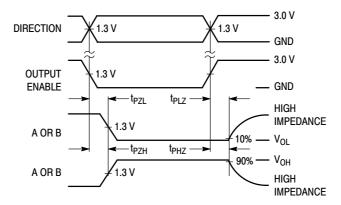
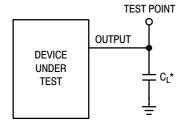


Figure 3.



\*Includes all probe and jig capacitance

DEVICE UNDER TEST  $\begin{array}{c|c} & & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & &$ 

\*Includes all probe and jig capacitance

Figure 4.

Figure 5. Test Circuit

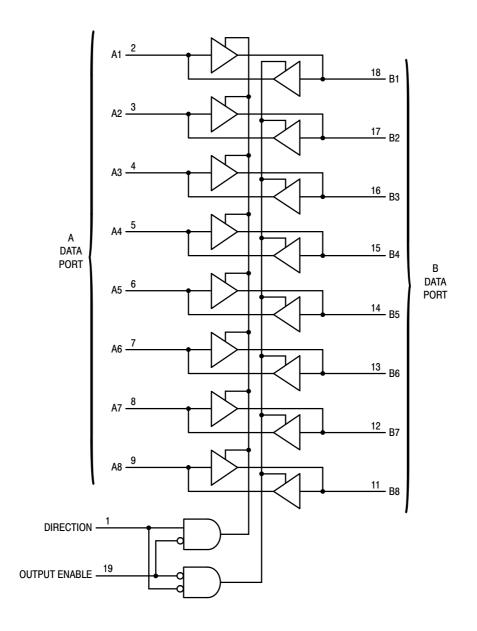


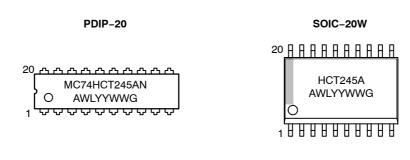
Figure 6. Expanded Logic Diagram

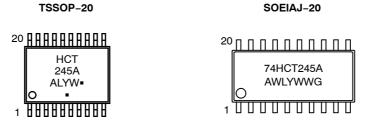
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74HCT245ANG	PDIP-20 (Pb-Free)	18 Units / Rail
MC74HCT245ADWG	SOIC-20 (Pb-Free)	38 Units / Rail
MC74HCT245ADWR2G	SOIC-20 (Pb-Free)	1000 / Tape & Reel
MC74HCT245ADTG	TSSOP-20*	75 Units / Rail
MC74HCT245ADTR2G	TSSOP-20*	2500 / Tape & Reel
MC74HCT245AFELG	SOEIAJ-20 (Pb-Free)	2000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **MARKING DIAGRAMS**



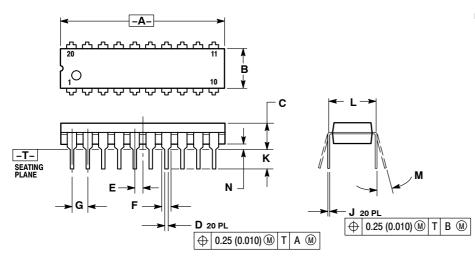


A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = = Pb-Free Package
(Note: Microdot may be in either location)

<sup>\*</sup>These packages are inherently Pb-Free.

#### PACKAGE DIMENSIONS

PDIP-20 **N SUFFIX** PLASTIC DIP PACKAGE CASE 738-03 ISSUE E



#### NOTES:

- IOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

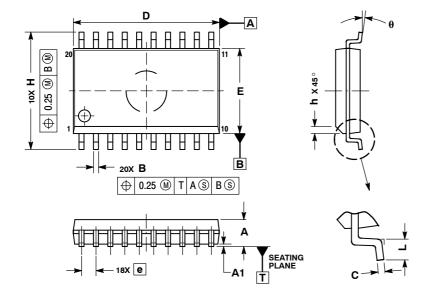
  2. CONTROLLING DIMENSION: INCH.

  3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	1.010	1.070	25.66	27.17
В	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050	BSC	1.27	BSC
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300	BSC	7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

#### SOIC-20W **DW SUFFIX** CASE 751D-05 **ISSUE G**



#### NOTES:

- OTES:

  DIMENSIONS ARE IN MILLIMETERS.

  INTERPRET DIMENSIONS AND TOLERANCES
  PER ASME Y14.5M, 1994.

  DIMENSIONS D AND E DO NOT INCLUDE MOLD
  PROTRUSION.

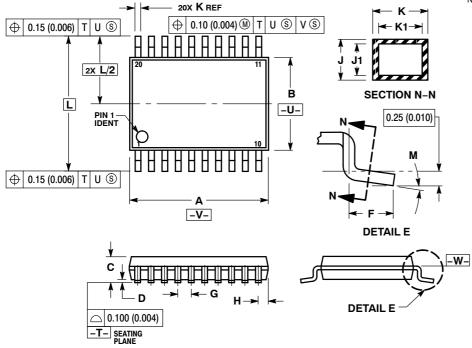
  MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

  DIMENSION B DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE PROTRUSION
  SHALL BE 0.13 TOTAL IN EXCESS OF B
  DIMENSION AT MAXIMUM MATERIAL
  CONDITION.

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
С	0.23	0.32		
D	12.65	12.95		
E	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
Δ.	00	70		

#### **PACKAGE DIMENSIONS**

#### TSSOP-20 **DT SUFFIX** CASE 948E-02 **ISSUE C**

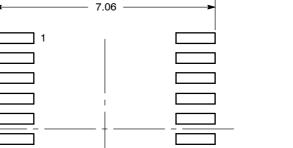


16X 0.36

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION:
  MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. CONDITION.
  - 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

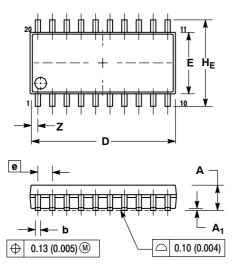
	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026	BSC
Н	0.27	0.37	0.011	0.015
_	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
٦	6.40	BSC	0.252 BSC	
М	0°	8°	0°	8°

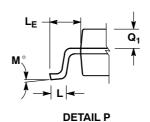


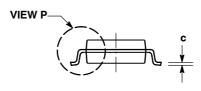
**SOLDERING FOOTPRINT** 

#### PACKAGE DIMENSIONS

SOEIAJ-20 **F SUFFIX** CASE 967-01 **ISSUE A** 







#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AUTO . .
   Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
   DIMENSIONS D AND E DO NOT INCLUDE
   MENSIONS D AND E DO NOT INCLUDE
   AND ARE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE, MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE. 4. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY. 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH
  DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 ( 0.018).

	MILLIN	MILLIMETERS INCH		HES
DIM	MIN	MAX	MIN	MAX
A A <sub>1</sub>		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.15	0.25	0.006	0.010
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0°	10°
$Q_1$	0.70	0.90	0.028	0.035
Z		0.81		0.032

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